

MBRJ10150CT

Rev.E Mar.-2016

/ Descriptions

TO-220S M M E $\approx g^{\sim}$ || 1 Schottky diode in a TO-220S Plastic Package.

/ Features

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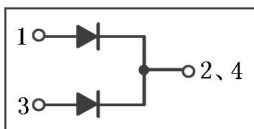
Low power loss, high efficiency.

/ Applications

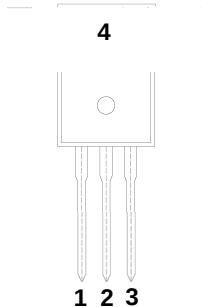
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For high frequency, high voltage, high current rectifier diode, freewheeling diode.

/ Equivalent Circuit



/ Pinning



PIN1 χ Anode

PIN 2 χ Cathode

PIN 3 χ Anode

PIN 4 χ NC

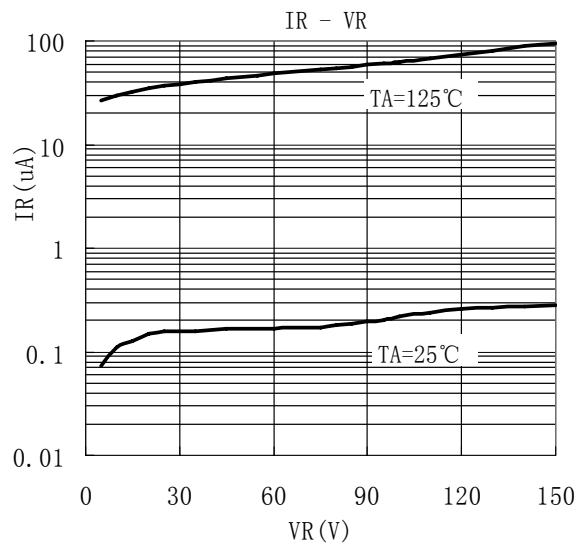
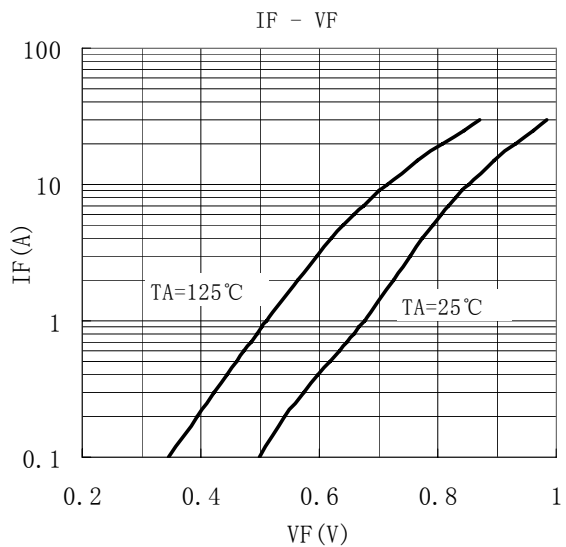
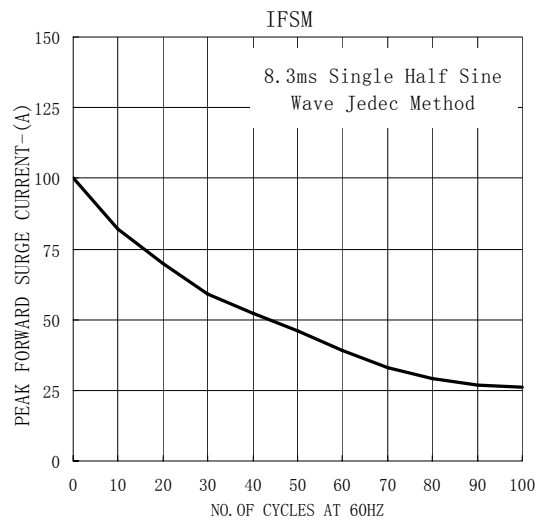
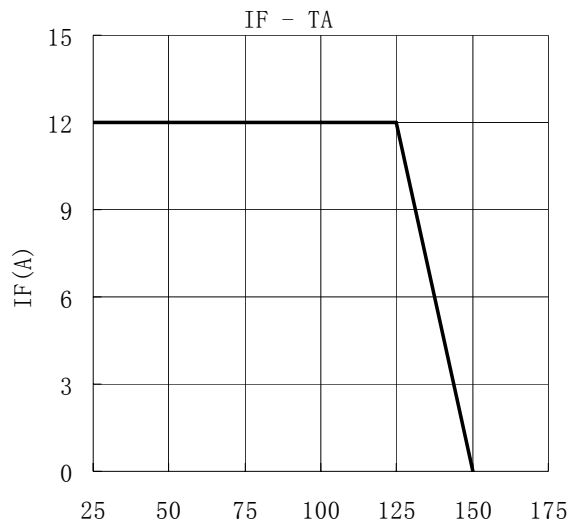
/ h_{FE} Classifications & Marking

ō M 1 ǒ " . See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	150	V
RMS Reverse Voltage	$V_{R(RMS)}$	105	V
Average Rectified Forward Current	$I_{F(AV)}$	2*5	A
Non Repetitive Peak Surge Current	I_{FSM}	100	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	3.5	/W
Junction Temperature Range	$T_{j MAX}$	150	
Storage Temperature Range	T_{stg}	-65~150	

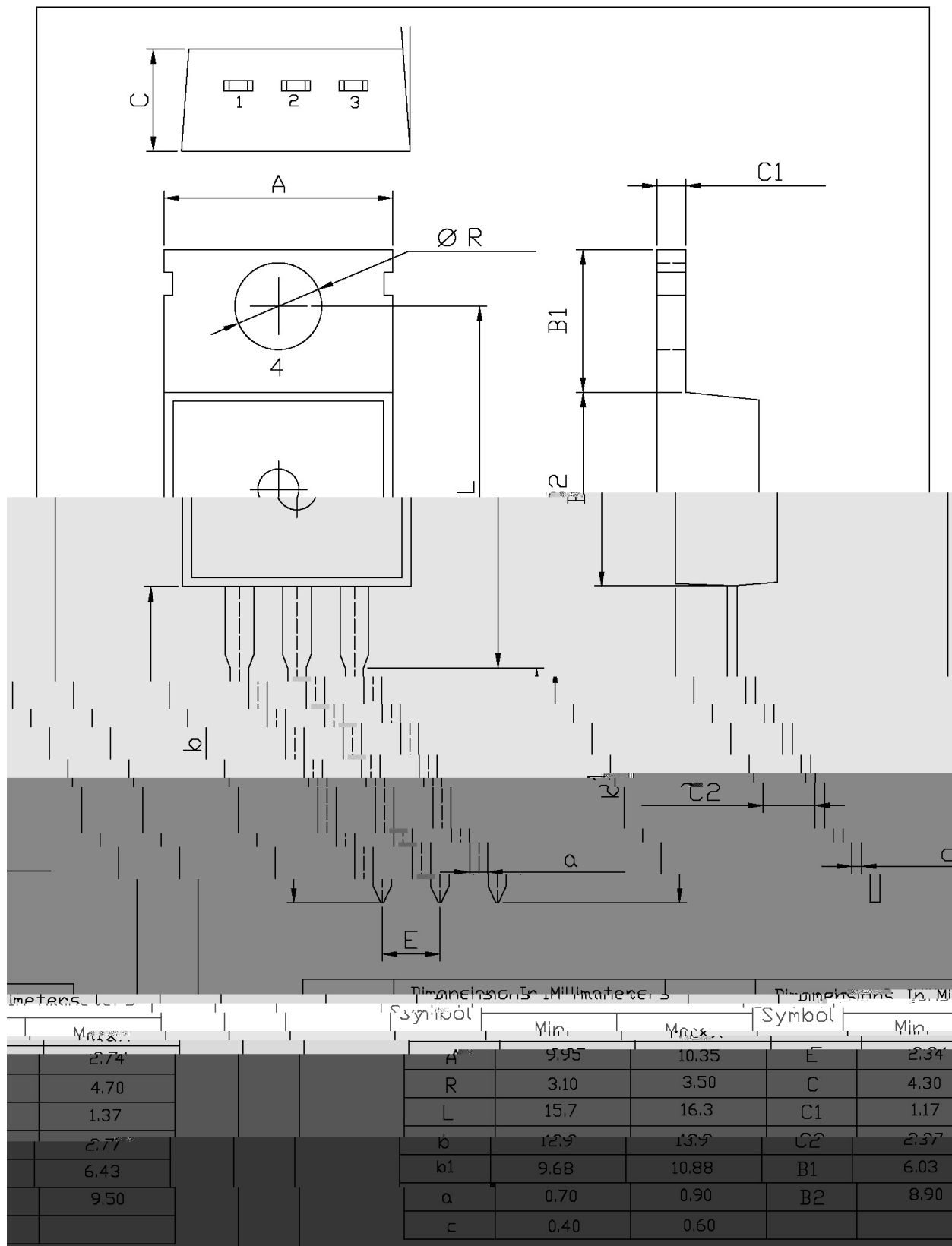
/ Electrical Characteristic Curve



/ Package Dimensions

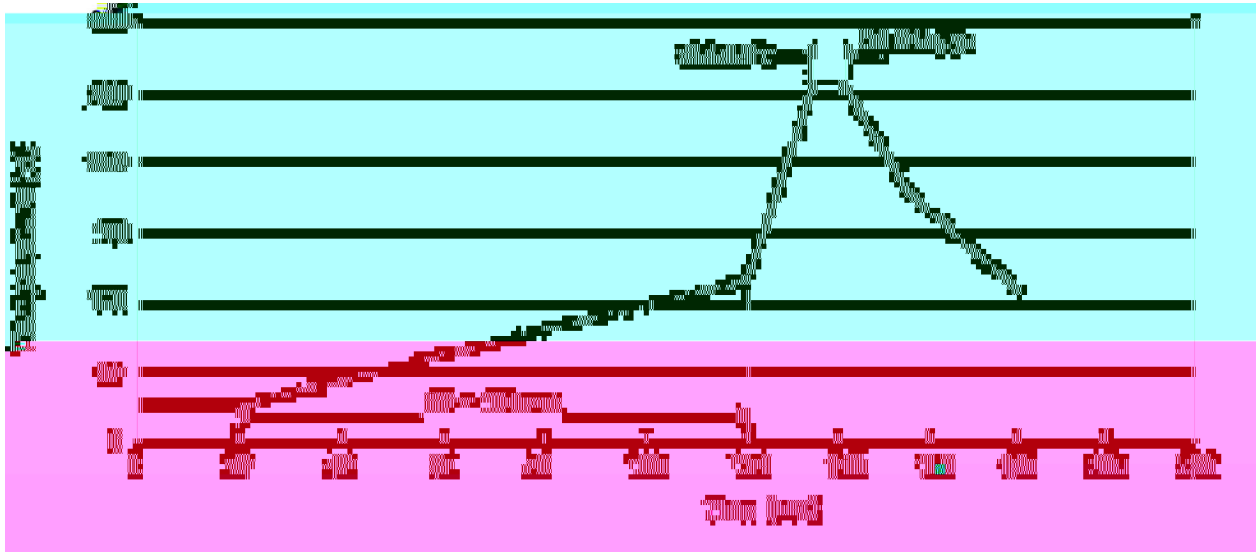
TO-220S

Unit: mm





() / Temperature Profile for Dip Soldering(Pb-Free)



℃

1. 25~150℃, Time: 60~90sec;

2. 255±5℃, Time: 5±0.5sec;

3. Cooling Speed: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.

2. Peak Temp.: 255±5℃, Duration: 5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

270±5℃

10±1 sec.

Temp.: 270±5

Time: 10±1 sec

/ Packaging SPEC.

1 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱